

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

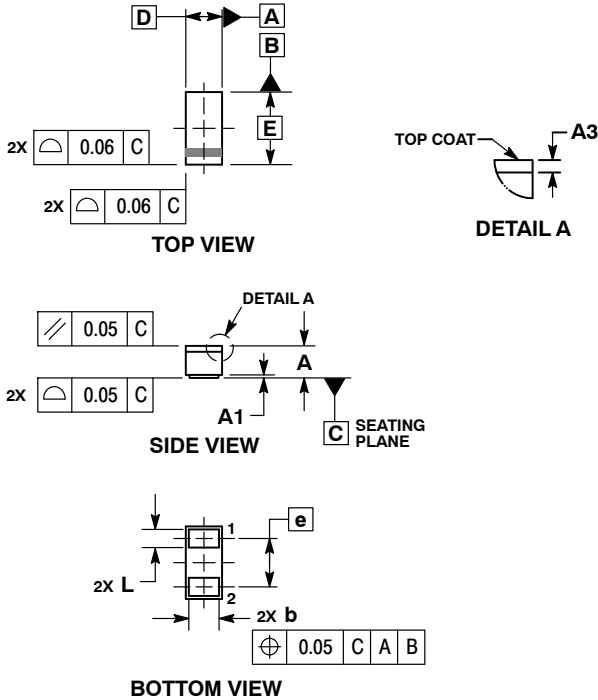
ON Semiconductor®



SCALE 8:1

DSN2, 0.6x0.3, 0.4P, (0201)  
CASE 152AS  
ISSUE A

DATE 23 JAN 2014



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS		
DIM	MIN	MAX
A	0.24	0.30
A1	0.00	0.01
A3	0.04	REF
b	0.20	0.25
D	0.30	BSC
E	0.60	BSC
e	0.40	BSC
L	0.10	0.18

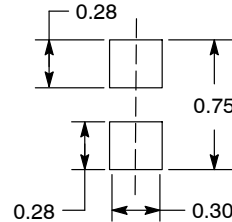
### GENERIC MARKING DIAGRAM\*



X = Specific Device Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

### MOUNTING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

See Application Note AND8398/D for more mounting details

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>DSN2, 0.6X0.3, 0.4P, (0201)</b>	<b>PAGE 1 OF 1</b>

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